

## FEATURES

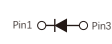
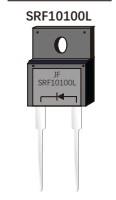
- Power pack
- Metal silicon junction ,majority carrier conduction
- Guard ring for overvoltage protection
- Low power loss ,high efficiency
- High current capability ,low forward voltage drop
- High forward surge capability
- High frequency operation
- Solder dip 275°C maximum,10s,per JESD22-B106
- Component in accordance to RoHS 2015/863/EU



TO-220AC



ITO-220AC



## MECHANICAL DATA

- Case: JEDEC TO-220AC、ITO-220AC
- Molding compound meets UL94V-0 flammability rating
- Terminals: Lead solderable per J-STD-002 and JESD22-B102
- Polarity: As marked
- Mounting Torque: 10 in-lbs maximum

## TYPICAL APPLICATIONS

For use in low voltage ,high frequency inverters ,DC/DC converters, free wheeling ,and polarity protection applications

### PRIMARY CHARACTERISTICS

IF(AV)	10A
VRRM	100V
IFSM	150A
VF at IF=10.0A(125°C)	0.63V
IR	20μA
TJ(MAX)	150°C
Package	TO-220AC, ITO-220AC
Diode variations	Single

## MAXIMUM RATINGS

(Ratings at 25°C ambient temperature unless otherwise specified )

Parameter	Symbol	Value	Unit
Maximum repetitive peak reverse voltage	VRRM	100	V
Maximum average forward rectified current (see fig.1)	IF(AV)	10.0	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC method at rated TL)	IFSM	150	A
Peak repetitive reverse current per diode at tp=2μs 1KHz	IRRM	0.5	A
Operating junction and Storage temperature range	TJ ,Tstg	-55 to+150	°C
Isolation voltage(ITO-220AB only)from terminals to heatsink t=1 min	VAC	1500	V

## RATINGS AND CHARACTERISTIC OF SR10100L,SRF10100L

### ELECTRICAL CHARACTERISTICS (T<sub>A</sub>=25°C Unless otherwise noted)

Parameter	Test Conditions		Symbol	TYP.	MAX.	Unit
Instantaneous forward voltage	I <sub>F</sub> =10.0A	T <sub>J</sub> =25°C	V <sub>F</sub> <sup>1)</sup>	0.66	0.70	V
		T <sub>J</sub> =100°C		0.64	—	
		T <sub>J</sub> =125°C		0.63	—	
	I <sub>F</sub> =5.0A	T <sub>J</sub> =25°C		0.53	0.57	
		T <sub>J</sub> =100°C		0.51	—	
		T <sub>J</sub> =125°C		0.50	—	
Reverse current	V <sub>R</sub> =100V	T <sub>J</sub> =25°C	I <sub>R</sub> <sup>2)</sup>	20	50	μA
		T <sub>J</sub> =100°C		2	5	mA
		T <sub>J</sub> =125°C		10	20	
Typical junction capacitance	4V,1MHz		C <sub>J</sub>	750		pF

Notes: 1.Pulse test: 300 μs pulse width,1% duty cycle

2.Pulse test: pulse width≤40ms

### THERMAL CHARACTERISTICS

Parameter	Symbol	SR10100L	SRF10100L	Unit
Typical thermal resistance <sup>3)</sup>	R <sub>θjc</sub>	2.5	4.5	°C/W

3.Thermal resistance from junction to case

### AVAILABLE PACK INFORMATION

Product code	Pack	Carton Size L×W×H(mm)	Inner Box Size L×W×H(mm)	Tube Length (mm)	Inner Box Number	Tube Number Per A Inner Box	Part Number Per A Tube	Quantity(carton) (K)
SR10100LCT TO-220AB	Tube	565×225×170	548×151×37	540	5	20	50	5
SRF10100LCT TO-220AB	Tube	565×225×170	548×151×37	540	5	20	50	5

FIG.1-FORWARD CURRENT DERATING CURVE

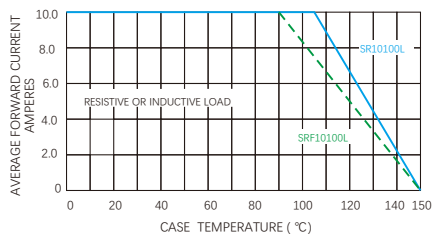


FIG.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

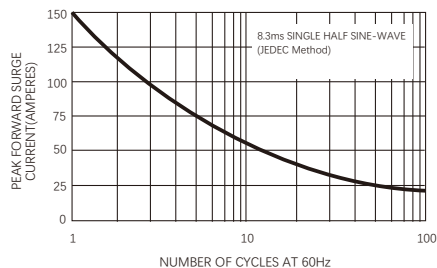


FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

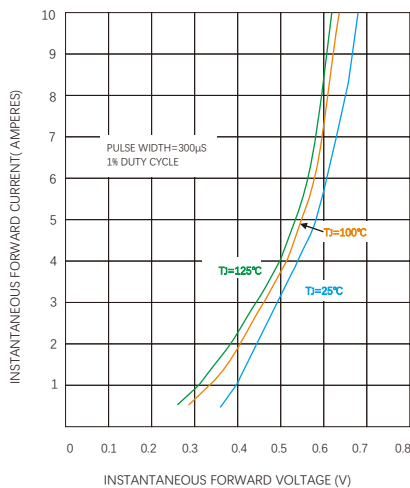


FIG.4-TYPICAL REVERSE CHARACTERISTICS

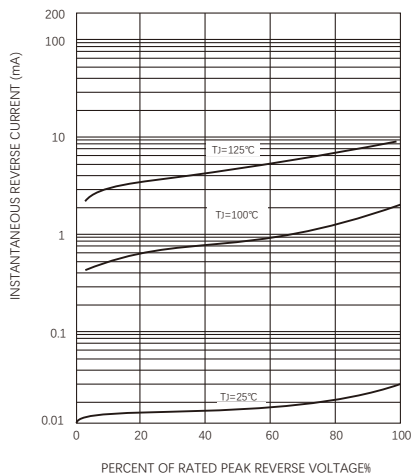
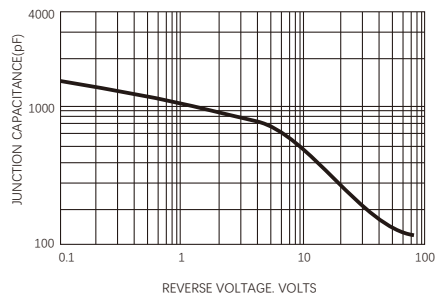
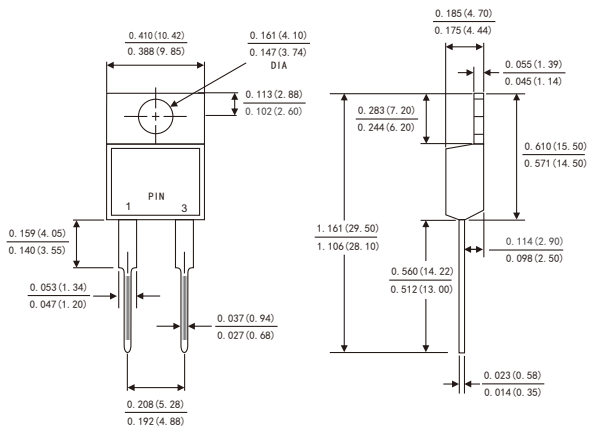


FIG.5-TYPICAL JUNCTION CAPACITANCE

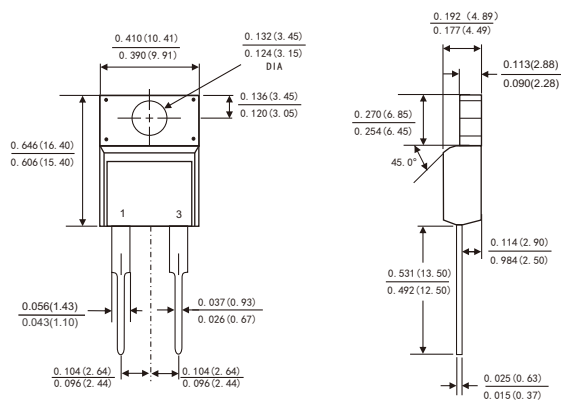


Dimensions in inches and (millimeters)

## TO-220AC



## ITO-220AC



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